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PATENT APPLICATION

Applicants: Kumar et al.

Case: 6492/ETCH/SILICON

Serial No.: 10/035,372 Filed: October 19, 2001

Group Art Unit: Not yet provided

Title: METHOD AND APPARATUS FOR DICING A SEMICONDUCTOR WAFER

THE COMMISSIONER OF PATENTS AND TRADEMARKS
Washington, D. C. 20231

S I R:

Disclosure Statement under 37 CFR 1.56 and 1.98

Pursuant to 37 CFR 1.56, the documents (copies enclosed) listed on form PTO-1449, submitted herewith, are disclosed. Under rule 37 C.F.R. 1.98(a), the applicants submit that no specific comments are necessary for any of the cited foreign language publications having an enclosed English language translation or abstract.

Respectfully submitted,

1-23-02
Date

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CERTIFICATE OF MAILING under 37 C.F.R. 1.8(a)

I hereby certify that this correspondence is being deposited on January 24, 2002 with the United States Postal Service as first class mail, with sufficient postage, in an envelope addressed to the Assistant Commissioner for Patents, Washington, D.C. 20231.

Khalid Zhai
Signature

1-24-02
Date of signature